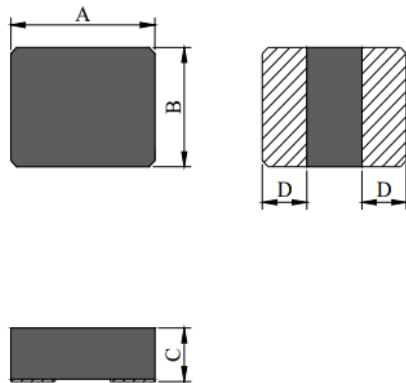


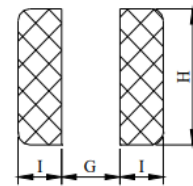
MMD252010-DCseries



SHAPE AND DIMENSIONS (mm)



RECOMMENDED PATTERN (mm)



Type	A	B	C	D	G	H	I
MMD252010	2.5±0.2	2.0±0.2	1.0Max.	0.9 ref.	1.0 ref.	2.3 ref.	0.9 ref.

APPLICATION

Laptop, Smartphone, LCD panel,
Bluetooth and other electronic devices

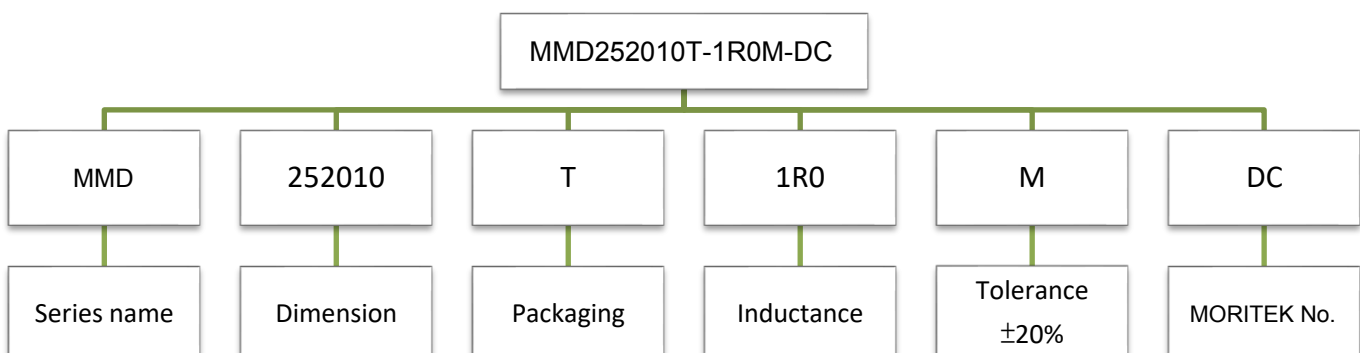
RATING

Operating Temperature : -55°C ~ +125°C
Storage Temperature : Under 40°C, Humidity < 75%

MATERIAL LIST

- a. Core : Alloy powder
- b. Wire : Enameled copper wire
- c. Terminal : Cu / Ni / Sn

PRODUCT IDENTIFICATION (ex.)



ELECTRICAL CHARACTERISTICS

Part No.	Inductance (uH)	Inductance tolerance	Test Frequency	DC Resistance (Ω)		Saturation current Isat(mA)		Temperature rise current Irms(mA)	
				Typ.	Max.	Typ.	Max.	Typ.	Max.
MMD252010T-R47M-DC	0.47	±20%	1MHz	0.015	0.022	6900	6500	6100	5600
MMD252010T-R68M-DC	0.68	±20%	1MHz	0.023	0.027	5900	5500	5600	5000
MMD252010T-1R0M-DC	1.0	±20%	1MHz	0.025	0.030	5300	4800	4500	4100
MMD252010T-1R5M-DC	1.5	±20%	1MHz	0.045	0.055	4300	3900	3400	3000
MMD252010T-2R2M-DC	2.2	±20%	1MHz	0.062	0.070	3300	3000	2700	2200
MMD252010T-3R3M-DC	3.3	±20%	1MHz	0.086	0.100	2800	2500	2500	2100
MMD252010T-4R7M-DC	4.7	±20%	1MHz	0.160	0.180	2600	2000	2000	1600
MMD252010T-6R8M-DC	6.8	±20%	1MHz	0.270	0.320	2400	1900	1600	1400
MMD252010T-100M-DC	10	±20%	1MHz	0.495	0.560	1550	1400	1050	950

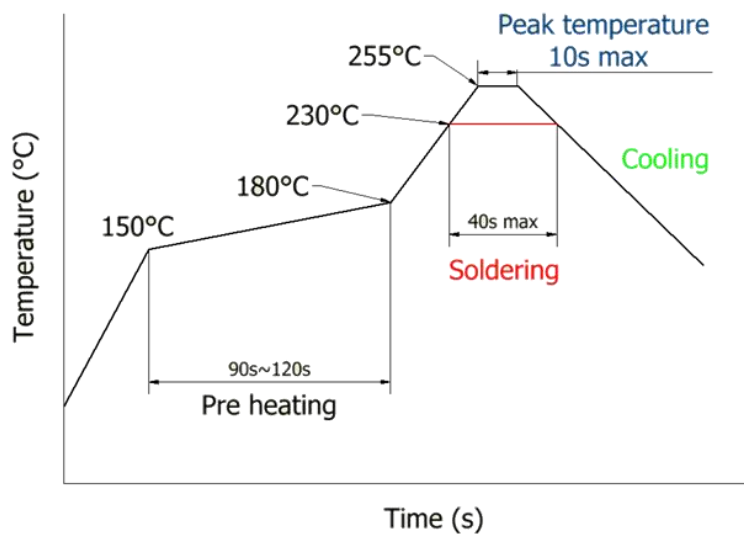
Note:

All test data is referenced to 25°C ambient

Isat base on $\Delta L / L0A=30$

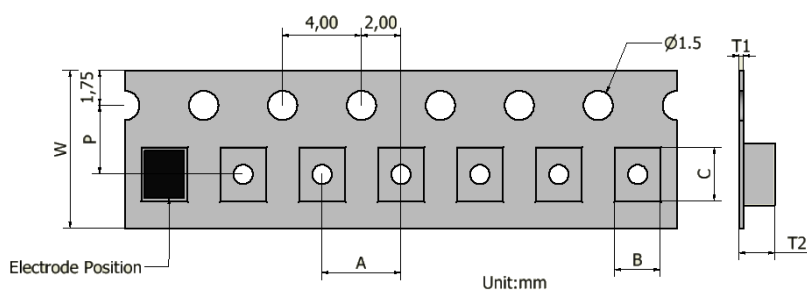
Irms base on Temp. rise 40

RECOMMENDED SOLDERING CONDITIONS



PACKAGE

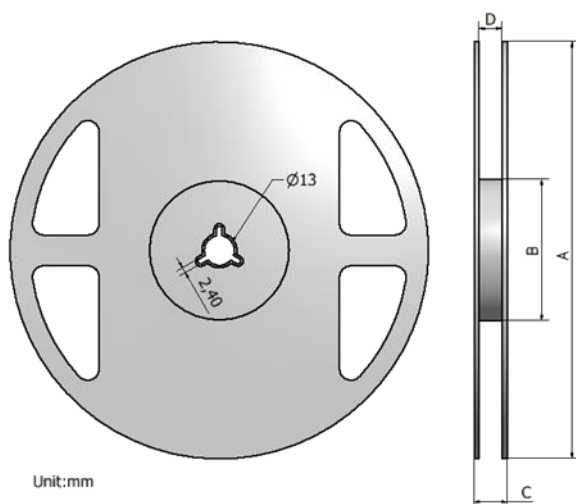
(1) Taping specifications



Type	W	P	A	B	C	T1	T2
MMD252010	8	3.5	4.0	2.3	2.7	0.23	1.2

(2) Reel specifications

Label



Molding Power Inductors
MMD252010T-□□□M-DC
3,000 PCS
Lot No. _____
MORITEK TECHNICAL CO., LTD.

Type	A	B	C	D	Q'ty/Reel
MMD252010	178	60	12	9	3000